

## 60V N-Channel Enhancement Mode MOSFET

### DESCRIPTION

The SMC2360 is the N-Channel logic enhancement mode power field effect transistor is produced using high cell density, advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. This device is suitable for use as a load switch or other general applications.

*SMC2360S-TRG ROHS Compliant This is Halogen Free*

### FEATURE

- ◆ 60V/6.0A,  $R_{DS(ON)} = 75m\Omega(typ.)@V_{GS} = 10V$
- ◆ 60V/3.0A,  $R_{DS(ON)} = 85m\Omega(typ.)@V_{GS} = 4.5V$
- ◆ Improved dv/dt capability
- ◆ Fast Switching
- ◆ 100% EAS Guaranteed
- ◆ Green Device Available

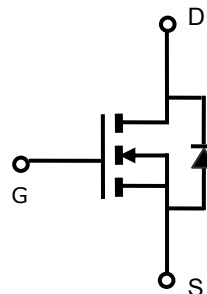
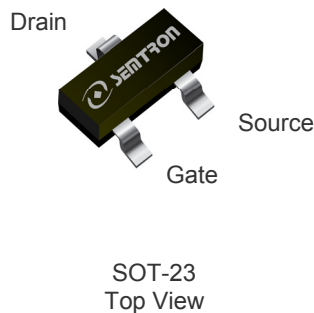
### APPLICATIONS

- ◆ Motor Drive
- ◆ Power Tools
- ◆ LED Lighting



N-Channel Enhancement Mode MOSFET

### PIN CONFIGURATION



### PART NUMBER INFORMATION

<p><b>SMC 2360 S - TR G</b></p> <p>a      b      c      d      e</p>	<p>a : Company name.  b : Product Serial number.  c : Package code.  d : Handling code  e : Green product code</p>
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## ORDERING INFORMATION

Part Number	Package Code	Handling Code	Shipping
SMC2360S-TRG	S : SOT-23	TR : Tape&Reel	3K/Reel

- ※ Year Code : 0 ~ 9, 2010 : 0
- ※ Week Code : A(1~2) ~ Z(53~54)
- ※ SOT-23 : Only available in tape and reel packaging.

## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C Unless otherwise noted )

Symbol	Parameter	Typical	Unit
V <sub>DSS</sub>	Drain-Source Voltage	60	V
V <sub>GSS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Continuous Drain Current (T <sub>C</sub> =25°C) <sup>A</sup>	V <sub>GS</sub> =10V	6.1
	Continuous Drain Current (T <sub>C</sub> =100°C) <sup>A</sup>		3.9
I <sub>DM</sub>	Pulsed Drain Current <sup>B</sup>	24	A
P <sub>D</sub>	Power Dissipation	T <sub>A</sub> =25°C	1.56
		T <sub>A</sub> =70°C	1.02
T <sub>J</sub>	Operation Junction Temperature	-50 to 150	°C
T <sub>STG</sub>	Storage Temperature Range	-50 to 150	°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.  
 Absolute maximum ratings are stress ratings only and functional device operation is not implied.

## THERMAL DATA

Symbol	Parameter	Typ	Max	Unit	
R <sub>θJA</sub>	Thermal Resistance-Junction to Ambient <sup>A</sup>	Steady-State	-	120	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Lead <sup>A</sup>	Steady-State	-	85	°C/W

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ Unless otherwise noted )

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2		2.5	V
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 12V$			$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V, T_J=25^\circ\text{C}$			1	$\mu A$
		$V_{DS}=48V, V_{GS}=0V, T_J=125^\circ\text{C}$			10	
$R_{DS(ON)}$	Drain-source On-Resistance <sup>B</sup>	$V_{GS}=10V, I_D=6.0A$ $V_{GS}=4.5V, I_D=3.0A$		75 85	85 100	m $\Omega$
$G_{fs}$	Forward Transconductance	$V_{DS}=10V, I_D=3A$		7		S
<b>Source-Drain Diode</b>						
$V_{SD}$	Diode Forward Voltage	$I_S=1.0A, V_{GS}=0V$		--	1.0	V
$I_S$	Continuous Source Current <sup>AD</sup>				6.1	A
<b>Dynamic Parameters</b>						
$Q_g$	Total Gate Charge	$V_{DS}=48V$		9.3	14	nC
$Q_{gs}$	Gate-Source Charge	$V_{GS}=10V$		2.1	4	
$Q_{gd}$	Gate-Drain Charge	$I_D=6.0A$		1.8	4	
$C_{iss}$	Input Capacitance	$V_{DS}=15V$		500	725	pF
$C_{oss}$	Output Capacitance	$V_{GS}=0V$		45	65	
$C_{rss}$	Reverse Transfer Capacitance	$f=1\text{MHz}$		16	30	
$t_{d(on)}$	Turn-On Time	$V_{DD}=30V$ $I_D=1.0A$		2.9	6	nS
$t_r$				9.5	18	
$t_{d(off)}$	Turn-Off Time	$V_{GS}=10V$ $R_G=3.3\Omega$		18.4	35	
$t_f$				5.3	10	

Note:

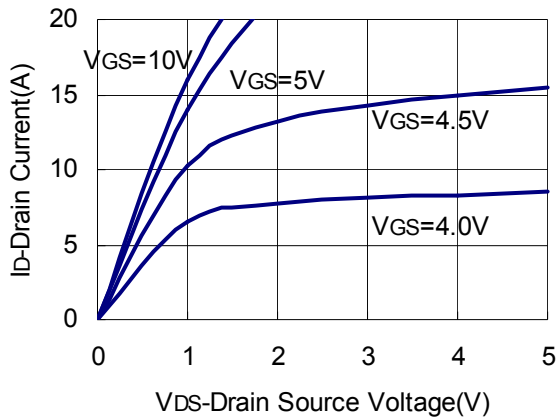
- The value of  $R_{\theta JA}$  is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ .
- The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- The EAS data shows Max. rating . The test condition is  $V_{DD}=-25V, V_{GS}=-10V, L=0.1\text{mH}$ .
- The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

The products and product specifications contained herein are subject to change without notice to improve performance characteristics. Consult us, or our representatives before use, to confirm that the information in this datasheet is up to date

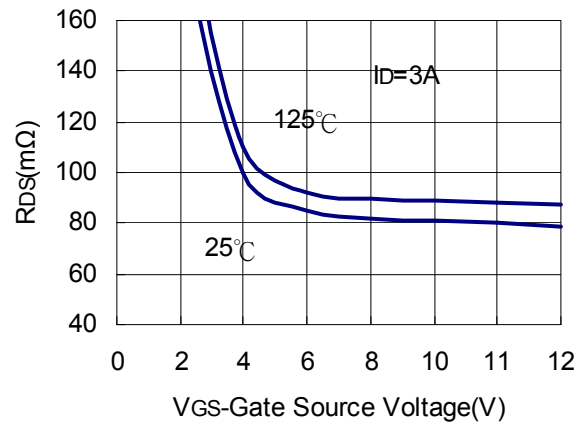
We assume no responsibility for any infringement of patents, patent rights, or other rights arising from the use of any information and circuitry in this datasheet.

## TYPICAL CHARACTERISTICS

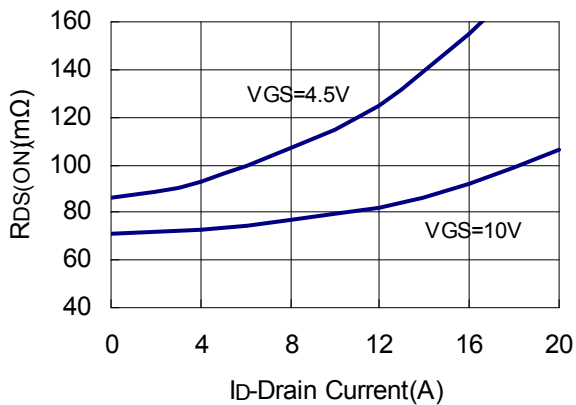
**Output Characteristics**



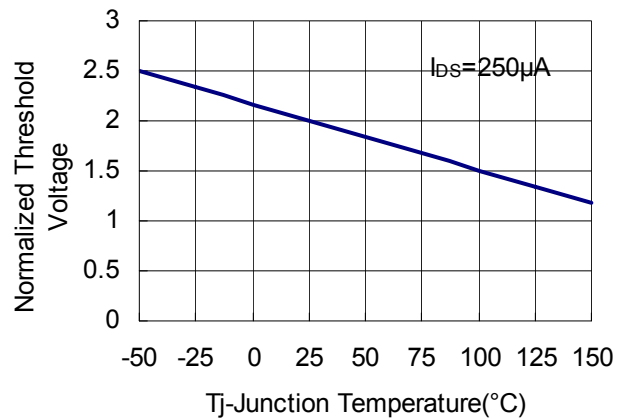
**Drain-Source On Resistance**



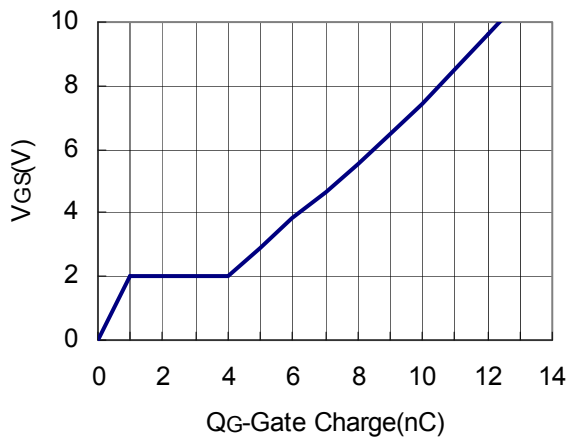
**Drain Source On Resistance**



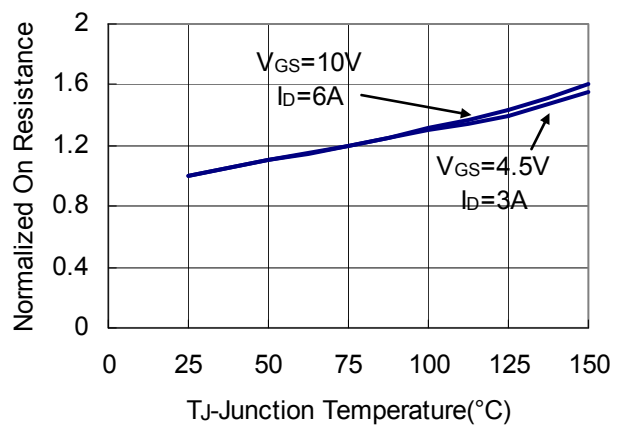
**Gate Threshold Voltage**



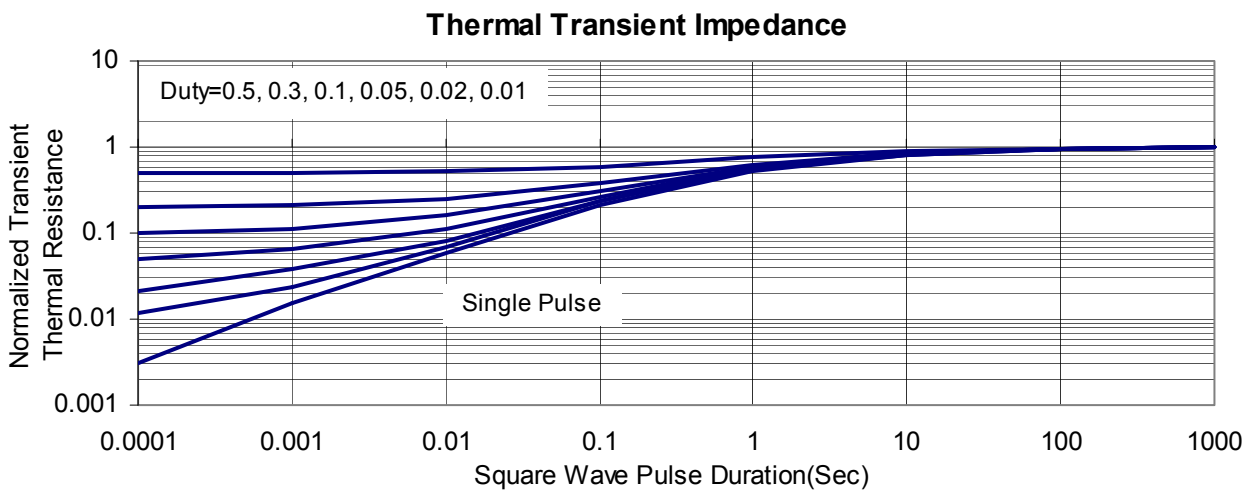
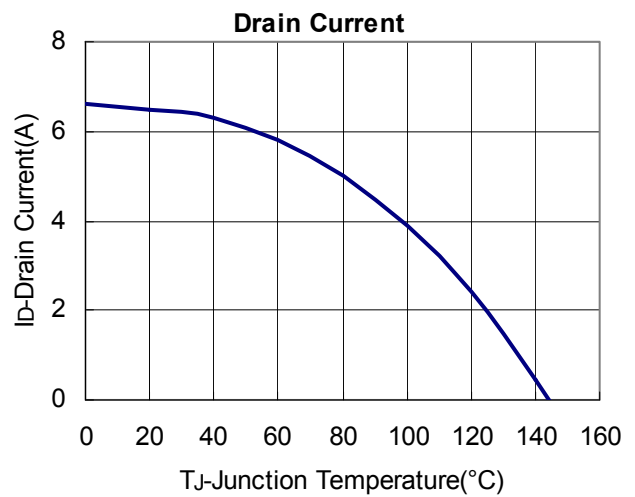
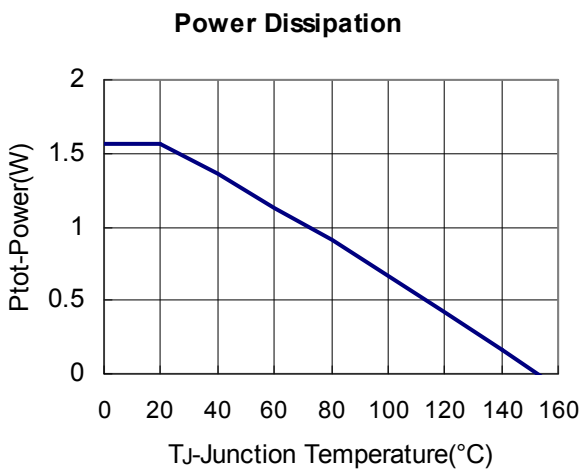
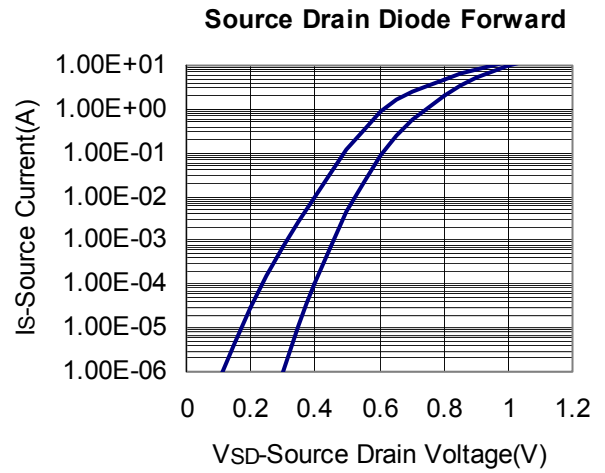
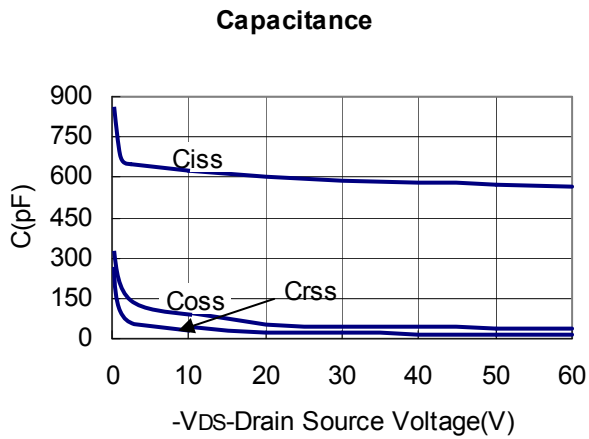
**Gate Charge**



**Drain Source On Resistance**



## TYPICAL CHARACTERISTICS



## ■ SOT-23 PACKAGE DIMENSIONS

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L1	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
$\theta$	0°	8°	0°	8°

